

[Name of Document] ABSTRACT

[Title] Alkaline etching solution for semiconductor wafer and alkaline etching method

5 Provided are an alkaline etching solution capable of improving a surface roughness even with a relatively low alkaline concentration, which has been conventionally widely used, an alkaline etching method using the solution, a method of manufacturing a silicon wafer, and further a silicon wafer
10 with its surface roughness improved, obtained through the method.

 The alkaline etching solution according to the present invention is a caustic alkaline aqueous solution containing bromate or a caustic alkaline aqueous solution containing
15 bromate and nitrate.

Fig. 1